SN54S482 ... J PACKAGE

SDLS212 D2112, MARCH 1976-REVISED OCTOBER 1980

- 4-Bit Slice is Cascadable to N-Bits
- Designed Specifically for Microcontroller/ Next-Address Generator Functions
- Increment/Decrement by One (Immediate or Direct Symbolic Addressing Modes)
- Offset, Vector, or Branch (Indexed or Relative Addressing Modes)
- Store Up to Four Returns or Links (Program Return Address from Subroutine)
- Program start or Initialize (Return to Zero or Clear Mode)
- On-Chip Edge-Triggered Output Register (Provides Steady-State Micro-Address/ Instruction)
- High-Density 20-Pin Dual-in-Line Package with 300-Mil Row Pin Spacing

description

The 'S482 is a high-performance Schottky TTL 4-bit-slice control element for use in any computer/control application requiring the coupling of high-performance bipolar speeds with the flexibility of microprogram control and bit-slice expandability. When used as a nextaddress generator, two 'S482 elements can address up to 256 words of microprogram; three elements can address up to 4096 words of microprogram; or a number of 'S482 elements can generate N words in multiples of four lines.

Comprised of an output register, push-pop stack, and a full adder, the 'S482 provides the capability to implement multiway testing needed to generate or to determine and select the source of the next function of microprogram address.

5N94546			CICAGL					
SN74S482	J(or n	PACKAGE					
(TOP VIEW)								
S4 [S3] C _{out} [S1] S2 [A3]	1 U 2 3 4 5 6 7	20 19 18 17 16 15 14	VCC CLK S5 S6 CLR F0 F1					
A2 A1 GND	8 9 10	13 12 11	F2 F3 A0					

SN54S482 ... FH PACKAGE SN74S482 ... FN PACKAGE (TOP VIEW)



TEXAS TEXAS TEXAS 75265

functional block diagram

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output register and source functions

The 4-bit edge-triggered register provides a steady-state output throughout each system clock cycle. An asynchronous clear extends the multiway testing to directly implement system initialization at ROM address zero.

Two source-select lines (S5, S6) provide the output register with access to either the current instruction (no change), an operand or address stored in the push-pop stack, the output of a four-function full adder, or a direct data-in address port. The sources and functions are summarized in Table I and II.

In bus applications, provision must be made to control negative spikes. When low, the output latches can be disturbed if the outputs are forced more negative than -0.5 V.

SEL	ECT	REGISTER INPUT SOURCE
S5	S 6	REGISTER INFOT SOURCE
L	Ł	DATA-IN PORT (Di)
L	н	FULL ADDER OUTPUTS (Σ)
н	L	PUSH-POP STACK OUTPUTS (Qi)
н	н	REGISTER OUTPUTS (HOLD)

TABLE I. REGISTER-SOURCE FUNCTIONS

H = high level, L = law level

QiA

		INPUTS			INTERNAL	OUTPUTS		
	S3	54	S5	S6	CLOCK	CK CLEAR QIA		Fi
HOLD	X	X	X	X	L	н	QiA0	FiO
CLEAR	X	х	х	x	х	L	QiA0	L
PUSH-POP	L	L	L	L		н	QiA0*	Di
STACK	L	L	L	н	1	н	QiA0*	Σi
"HOLD"	L	L	н	L	t	н	QiA0*	QiAO
	L	L	н	н	1	н	QiA0*	Fi0
PUSH-POP	L	н	L	L	1	н	£i*	Di
STACK	L	н	L	н	1	н	≌i*	Σi
"LOAD"	L,	н	н	L	t	н	<u>∑</u> i*	QiAO
LUAD		н	н	н	†	н	∑i*	Fi0
PUSH-POP	н	L	L.	L	t	н	QiB0 [†]	Di
STACK	Гн	L	L	н	t	н	QiB0 [†]	Σi
"POP"	н	L	н	L	1	н	QiB0 [†]	QiAO
	н	L	т	н	1	н	QiB0 [†]	FiÓ
PUSH-POP	н	н	L	L	t	н	Σi‡	Di
STACK	Н	н	L	Н	1	н	Σi‡	Σi
"PUSH"	н	н	н	L	Ť	н	Σi‡	QiA0
	н	н	Н	н	†	н	Σi∓	Fi0
MSR LSB = 3, 2, 1, 0 Ai = Data inputs DiA = Push-pop stack word DiAO = the level of Qi befo inputs conditions w	re the i	ndic	ated		FiO \cong $\Sigma i \equiv \lambda$ *QiB, [†] QiDO	conditior Adder out QiC, QiD → QiD,	tputs of Fi before th is were establi puts (internal) do not change QiD0 \rightarrow QiC, (QiB0 \rightarrow QiC, (shed a DiC0 → QiB,

TABLE II. PUSH-POP STACK CONTROL AND REGISTER-SOURCE FUNCTIONS

push-pop stack control

The 4-word push-pop stack can be used for nesting up to four levels of program or return (link) addresses. In the load mode, the first (top) word is filled with new data from the output of the full adder, and no push occurs meaning that previous data at that location is lost. However, all other word locations in the push-pop stack remain unchanged. In the push mode, the new word is again entered in the first (top) location; however, previous data residing in the top three words are pushed down one word location and retained at their new locations. The bottom word is written over and lost.

In the pop mode, words in the push-pop stack move up one location on each clock transition. A unique function is provided by the bottom (fourth) register as its content is retained during the pop mode, and after 3 clock transitions, all words in the stack are filled with the operand/address that occupied the bottom register.

The operand/address will remain available indefinitely if stack functions are limited to the pop or hold modes.

The push-pop stack functions are shown in Tables II and III.

	FUNCTION	SEL.		REG.	REG.	REG.	REG.	INPUT/			
	FUNCTION	S 3	<u>\$4</u>	D	с	8	A	OUTPUT			
BIT 0	LOAD	L	н	QIDO	QiC0	QiBO	÷ Σi	Σί ΙΝ			
ВІТ 1	PUSH	н	н	← QiCû	← QiB0	← QiA0	÷ Σi	ΣίΙΝ			
BIT 2	POP	н	L	-	→ QiD0	 QiC0	-→ QiB0	QIA OUT			
BIT 3	HOLD	L	L	Q:D0	QiCO	QiBO	QiAÛ	QIA OUT			

TABLE III. PUSH-POP STACK FUNCTIONS

µlink operations show previous data location after clock transition.

full adder

The four-function full adder is controllable from select inputs S1 and S2 to perform:

A or B incrementation, or decrementation of B Unconditional jumps or relative offsets No change Return to zero or one

Incrementation can be implemented by forcing a carry (high) into the ALU. In this mode either of the following options are possible:

- 1. Increment (A plus zero plus carry)
- 2. Increment B (zero plus B plus carry), or decrement B (all highs at A then A plus B with carry input low and disregard, don't use, carry out)
- 3. Increment the jump or offset (A plus B plus carry)
- 4. Start at zero or one and increment on each clock (select zero plus zero plus carry, then select zero plus B plus carry), or set register to N and decrement B (see 2 above).
- No change (carry input is always active and removal of carry combined with either the ALU or register hold mode will retain the current address).

Unconditional jumps can be implemented by applying and selecting the jump directly from the data inputs to the output register. Offset can be accomplished by summing the output register with the offset magnitude (A plus B) with carry low.

The ALU functions are shown in Table IV.

	INP	UTS	INTERNAL
	S1	S2	Σι
-	н	н	0 PLUS 0 PLUS C-in
	H L		0 PLUS Bi PLUS C-in
	L	н	Ai PLUS 0 PLUS C-in
	L	L	Ai PLUS Bi PLUS c-in

TABLE IV. ADDRESS CONTROL FUNCTIONS

compound generator functions

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As the function-select lines of the register sources, push-pop stack, and adder are independent, compound , functions can be selected to occur on the next clock transition.

Subroutine branches and returns can be simplified by saving the return or link addresses in the push-pop stack. This branch-and-save function can be accomplished on the same clock time as follows:

DATA-IN	ADDER	PUSH-POP STACK	REGISTER SOURCE
Branch address	Zero plus 8 plus one	Push	Data-in
	(S1 = H, S2 = L)	(S3 = S4 = H)	(S5 = S6 = L)

Up to four branches can be made with the return stored in the 4-word push-pop stack.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1) 7 V	/
Input voltage	/
Off-state output voltage	/
Operating free-air temperature range: SN54S482	2
SN74S482	2
Storage temperature range	2

NOTE 1. All voltage values are with respect to network ground terminal.

recommended operating conditions

			S	SN54S482 SN74S482			2			
			MIN	NOM	MAX	MIN	NOM	MAX		
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.8			0.8	V	
1	High lovel output ourget	Cout			- 1		-	- 1		
ЮН	High-level output current	Any F		· · · ·	- 2	1		- 2	mA	
10.	Low-level output current	Cout			10			10		
IOL		Any F			16			16	mΑ	
+	Pulse duration	CLK high or fow	50			30				
tw		CLR low	15			15			ns	
	Setup time, before CLK1	Data-in, S5, S6	0			0				
		Data-in via adder to stack	35			30				
		Data-in via adder to output latch	25			20			ns	
tsu		S1, S2	40			30				
		\$3, \$4	20			15				
		CLR, inactive state	0			0				
tr	CLK input rise time		20			25			ns	
	· · ·	Data-in, S5, S6	30			25				
+.	Hold time often CLK1	Data-in via adder	15			10			ns	
th	Hold time, after CLK1	\$1, \$2	15			10				
		53, 54	25			20				
† _A	Operating free-air temperatur	e	- 55		125	0		70	°C	



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PARAMETER				S	N54\$4	82	SN	174548	2	
	PARAMETER	TEST CON	TEST CONDITIONS [†]		TYP [‡]	MAX	MIN	түр‡	MAX	UNIT
ViK		$V_{CC} = MIN$,	lլ = -18 mA			-1.2			- 1.2	V
∨он	Cout	$V_{CC} = MIN,$	lон = -1 mA	2.5	3.4		2.7	3.4		>
•OH _	Αηγ Ε	$V_{CC} = MIN$,	$I_{OH} = -2 \text{ mA}$	2.5	3.4		2.7	3.4		v
Va	Cout	$V_{CC} = MIN$,	I _{OL} = 10 mA			0.5			0.5	v
VOL	Any F	$V_{CC} = MIN$	l _{OL} = 16 mA			0.5			0.5	, v
4		$V_{CC} = MIN,$	$V_1 = 5.5 V$			1			1	mΑ
	\$1, \$2, C _{in}	V _{CC} = MAX,				50			50	μA
1	S3, S4, S5, S6, CLK		$V_{1} = 2.7 V_{1}$			0.1			0.1	
ΗI	CLR		$v_1 = 2.7 v_2$			0.25			0.25	mA
	Any A					0.15			0.15	
	S1, S2					- 1			- 1	
	Cin					-0.8			-0. <u>8</u>	
1	S3, S4	$V_{CC} = MAX_{c}$				-1.2			- 1.2	mA
կլ	Any A, S5, S6	ACC = MWY	vi = 0.5 v			- 2	_		- 2	
	CLR					-4	Ē.,		- 4	
	CLK					-2.8			- 2.8	
los		VCC = MAX		- 40		- 110	- 40		-110	mA
^I CC		Vcc = MAX			90	130		90	140	mA

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. [‡]All typical values are at $V_{CC} = 5 V$, $T_A = 25 °C$.

[§]Not more than one output should be shorted at a time.

switching characteristics (see Note 1)

PARAMETER	ARAMETER FROM (INPUT)	TO (OUTPUT)	V _{CC} = MIN to MAX $C_L = 15 pF$ $R_L = 280 \Omega$ $T_A = MIN$ to MAX						
			SN54S482 SN74S48				2		
			MIN TYP [‡]	MAX	MIN	түр‡	MAX	7	
^t PLH	CLK	A 5	12	30		12	25	ns	
^t PHL	CLK	Any F	15	30		15	25	115	
tPHL	CLR	Any F	12	25		12	20	ns	
tPLH	0		12	22		12	18		
^t PHL	C _{in}	C _{out}	10	22		10	18	ns	
^t PLH	Δημ. Δ	<u>с</u>	17	30		17	25	ns	
^t PHL	Any A C _{out}	vout	12	30		12	23	''	

[‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

NOTE 1: See General Information Section for load circuit and voltage waveforms.



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